

## Solderable GaAs Constant Gamma Flip-Chip Varactor Diode

V3

### Features

- Usable Past 70GHz
- Constant Gamma for Linear Tuning
- Low Parasitic Capacitance
- High Q
- Silicon Nitride Passivation
- Polyimide Scratch Protection
- Surface Mount Configuration
- Lead Free (RoHs Compliant)
- Available in Pocket Tape and Reel.
- Can withstand 500 Temperature Cycles (-65 Deg.C. to +150 Deg.C), mounted with 96.5Sn/3.5Ag solder without Mechanical Degradation.
- Can be Mounted with Solder or Conductive Epoxy.

### Description

M/A-COM Technology Solutions' MAVR-000120-1411 is a gallium arsenide flip chip hyperabrupt varactor diode. This device is fabricated on OMCVD epitaxial wafers using a process designed for high device uniformity and extremely low parasitics. This diode is fully passivated with silicon nitride and has an additional layer of polyimide for scratch protection. The protective coatings prevent damage to the junction during automated or manual handling. The flip chip configuration is suitable for pick and place insertion.

### Ordering Information

Part Number	Package
MAVR-000120-14110P	Pocket Tape
MAVR-000120-14110G	Gel Pack

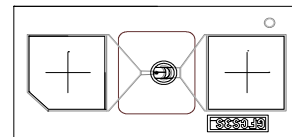
### Absolute Maximum Ratings <sup>1,2</sup>

Operating Temperature	-40°C to +125°C
Storage Temperature	-65°C to +150°C
Power Dissipation	100 mW
Mounting Temperature	+260C

1. Exceeding any one or combination of these limits may cause permanent damage to this device.
2. M/A-COM does not recommend sustained operation near these survivability limits.

### Chip Layout

#### Front View (Circuit Side)



#### Back View (Operator Side)



1

**ADVANCED:** Data Sheets contain information regarding a product M/A-COM Technology Solutions is considering for development. Performance is based on target specifications, simulated results, and/or prototype measurements. Commitment to develop is not guaranteed.

**PRELIMINARY:** Data Sheets contain information regarding a product M/A-COM Technology Solutions has under development. Performance is based on engineering tests. Specifications are typical. Mechanical outline has been fixed. Engineering samples and/or test data may be available. Commitment to produce in volume is not guaranteed.

• North America Tel: 800.366.2266 • Europe Tel: +353.21.244.6400  
• India Tel: +91.80.43537383 • China Tel: +86.21.2407.1588

Visit [www.macomtech.com](http://www.macomtech.com) for additional data sheets and product information.

M/A-COM Technology Solutions Inc. and its affiliates reserve the right to make changes to the product(s) or information contained herein without notice.

# MAVR-000120-1411

## Solderable GaAs Constant Gamma Flip-Chip Varactor Diode

V3

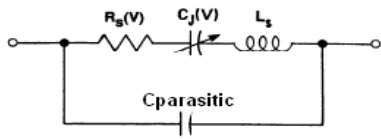
### Electrical Specifications @ $T_A = +25\text{ }^\circ\text{C}$

Breakdown Voltage @  $I_R = 10\text{mA}$ ,  $V_b = 20\text{ V}$  Minimum  
 Reverse Leakage Current @  $V_R = 14\text{V}$ ,  $I_R = 100\text{ nA}$  Maximum

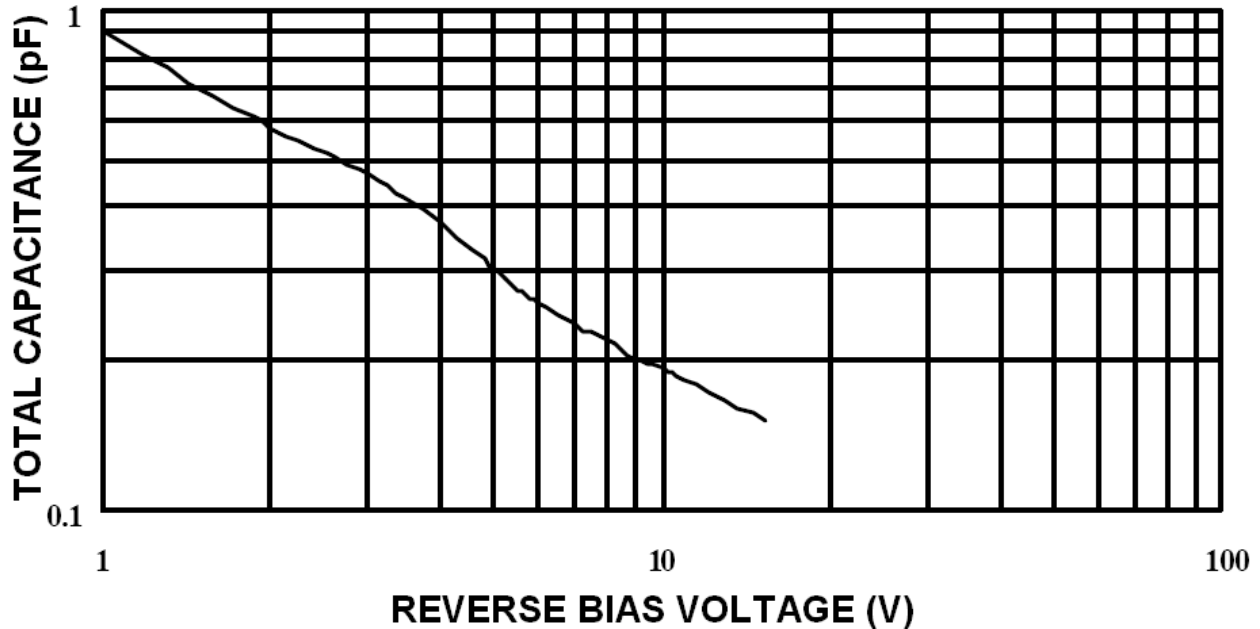
Part Number	Ct (pF)			Ct (pF)			Ct (pF)			Q Factor (pF)			Gamma (pF)		
	f=1MHz, $V_R = 0\text{ V}$			f=1MHz, $V_R = 4\text{ V}$			f=1MHz, $V_R = 10\text{ V}$			f=50MHz, $V_R = 4\text{ V}$			$V_R = 2\text{-}12\text{V}$		
	Min.	Typ.	Max.	Min.	Typ.	Max.	Min.	Typ.	Max.	Min.	Typ.	Max.	Min.	Typ.	Max.
MAVR-000120-1141	1.1			0.30	0.40		0.14	0.20		3000			0.9	1.1	

### Schematic

FLIPCHIP TUNING VARACTOR EQUIVALENT CIRCUIT



**TYPICAL PERFORMANCE CURVE @ +25 °C**  
**CAPACITANCE VS VOLTAGE**  
**GAMMA = 1.00 +/- 10% FROM 2 to 12 Volts**



2

\* Specifications are subject to change without prior notification

**ADVANCED:** Data Sheets contain information regarding a product M/A-COM Technology Solutions is considering for development. Performance is based on target specifications, simulated results, and/or prototype measurements. Commitment to develop is not guaranteed.

**PRELIMINARY:** Data Sheets contain information regarding a product M/A-COM Technology Solutions has under development. Performance is based on engineering tests. Specifications are typical. Mechanical outline has been fixed. Engineering samples and/or test data may be available. Commitment to produce in volume is not guaranteed.

• North America Tel: 800.366.2266 • Europe Tel: +353.21.244.6400  
 • India Tel: +91.80.43537383 • China Tel: +86.21.2407.1588  
 Visit [www.macomtech.com](http://www.macomtech.com) for additional data sheets and product information.

M/A-COM Technology Solutions Inc. and its affiliates reserve the right to make changes to the product(s) or information contained herein without notice.

### Mounting Techniques

Die attach for these devices is made simple through the use of surface mount die attach technology. This chip was designed to be inserted onto hard or soft substrates with the junction side down. This chip can be mounted with conductive epoxy or with solder.

### Solder Die Attach:

This device can be mounted with Sn63/Pb37 or RoHS compliant solder. Typical reflow profiles are provided on M/A-Com application note M538, "Surface Mounting Instructions" which can be found @ [www.macomtech.com](http://www.macomtech.com)

### Epoxy Die Attach:

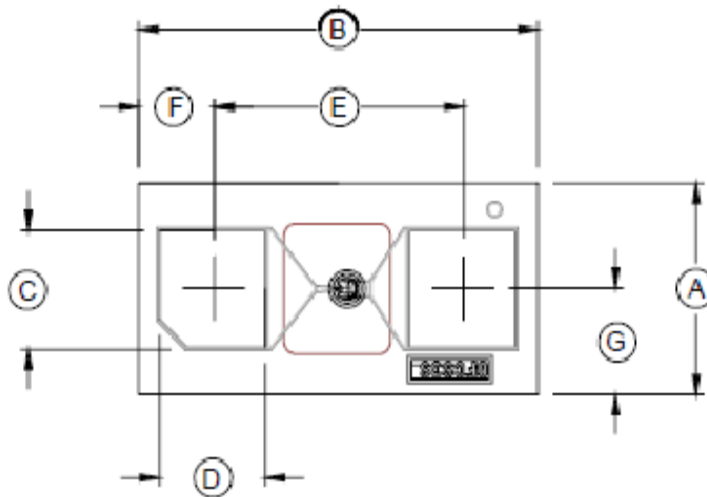
This device can also be attached with conductive epoxy. The assembly can be preheated to 125 - 150°C. Use a minimum amount of epoxy. Cure epoxy as per manufacturer's instructions.

### Handling Procedures

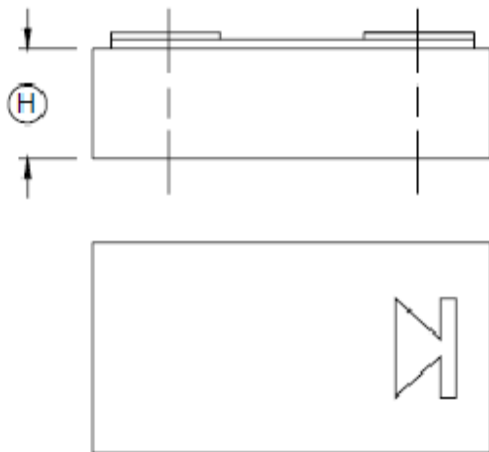
The following precautions should be observed to avoid damaging these chips:

- Cleanliness:** The chips should be handled in a clean environment. Do not attempt to clean die after installation.
- Static Sensitivity:** Semiconductor devices are ESD sensitive and can be damaged by static electricity. Proper ESD techniques should be used when handling these devices.
- General Handling:** The protective polymer coating on the active areas of these die provides scratch protection, particularly for the metal air bridge which contacts the anode. Die can be handled with tweezers or vacuum pickups and are suitable for use with automatic pick-and-place equipment.

### Flip Chip Outline Drawing



Case Style 1500



DIM.	INCHES		MILLIMETERS	
	MIN.	MAX.	MIN.	MAX.
A	0.015	0.017	0.381	0.431
B	0.029	0.031	0.736	0.787
C	0.008	0.009	0.203	0.228
D	0.007	0.008	0.178	0.203
E	0.016	0.017	0.406	0.431
F	0.006	0.007	0.152	0.178
G	0.0075	0.0085	0.190	0.216
H	0.0075	0.0085	0.190	0.216

1. Pad finish is .2 microns of gold over 4 microns of nickel.

Компания «Life Electronics» занимается поставками электронных компонентов импортного и отечественного производства от производителей и со складов крупных дистрибьюторов Европы, Америки и Азии.

С конца 2013 года компания активно расширяет линейку поставок компонентов по направлению коаксиальный кабель, кварцевые генераторы и конденсаторы (керамические, пленочные, электролитические), за счёт заключения дистрибьюторских договоров

Мы предлагаем:

- Конкурентоспособные цены и скидки постоянным клиентам.
- Специальные условия для постоянных клиентов.
- Подбор аналогов.
- Поставку компонентов в любых объемах, удовлетворяющих вашим потребностям.
- Приемлемые сроки поставки, возможна ускоренная поставка.
- Доставку товара в любую точку России и стран СНГ.
- Комплексную поставку.
- Работу по проектам и поставку образцов.
- Формирование склада под заказчика.
- Сертификаты соответствия на поставляемую продукцию (по желанию клиента).
- Тестирование поставляемой продукции.
- Поставку компонентов, требующих военную и космическую приемку.
- Входной контроль качества.
- Наличие сертификата ISO.

В составе нашей компании организован Конструкторский отдел, призванный помогать разработчикам, и инженерам.

Конструкторский отдел помогает осуществить:

- Регистрацию проекта у производителя компонентов.
- Техническую поддержку проекта.
- Защиту от снятия компонента с производства.
- Оценку стоимости проекта по компонентам.
- Изготовление тестовой платы монтаж и пусконаладочные работы.



Тел: +7 (812) 336 43 04 (многоканальный)

Email: [org@lifeelectronics.ru](mailto:org@lifeelectronics.ru)